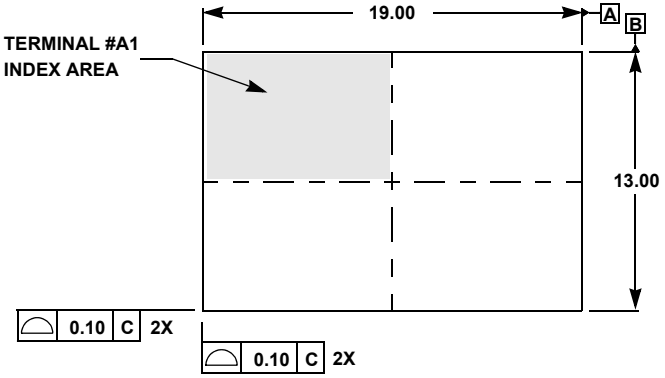
Package Outline Drawing

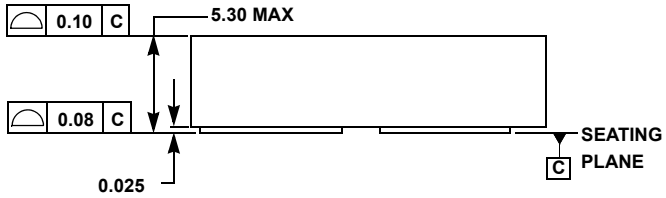
Y22.19x13

22 I/O 19mmx13mmx5.30mm HDA MODULE

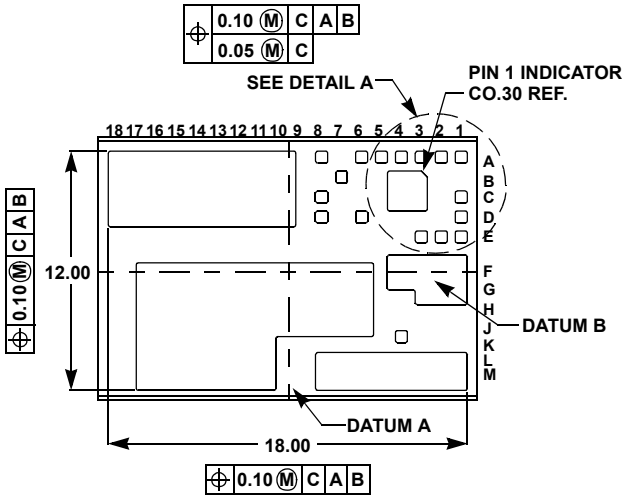
Rev 1, 11/16



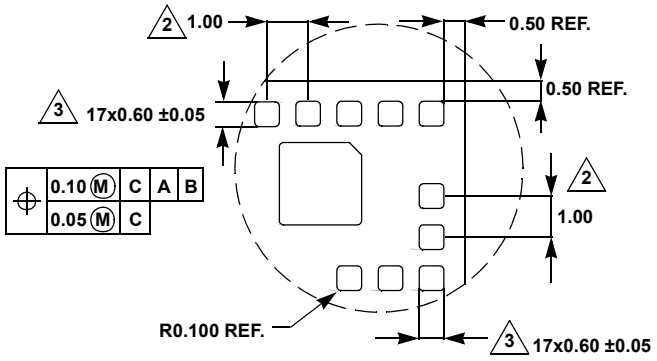
TOP VIEW



SIDE VIEW



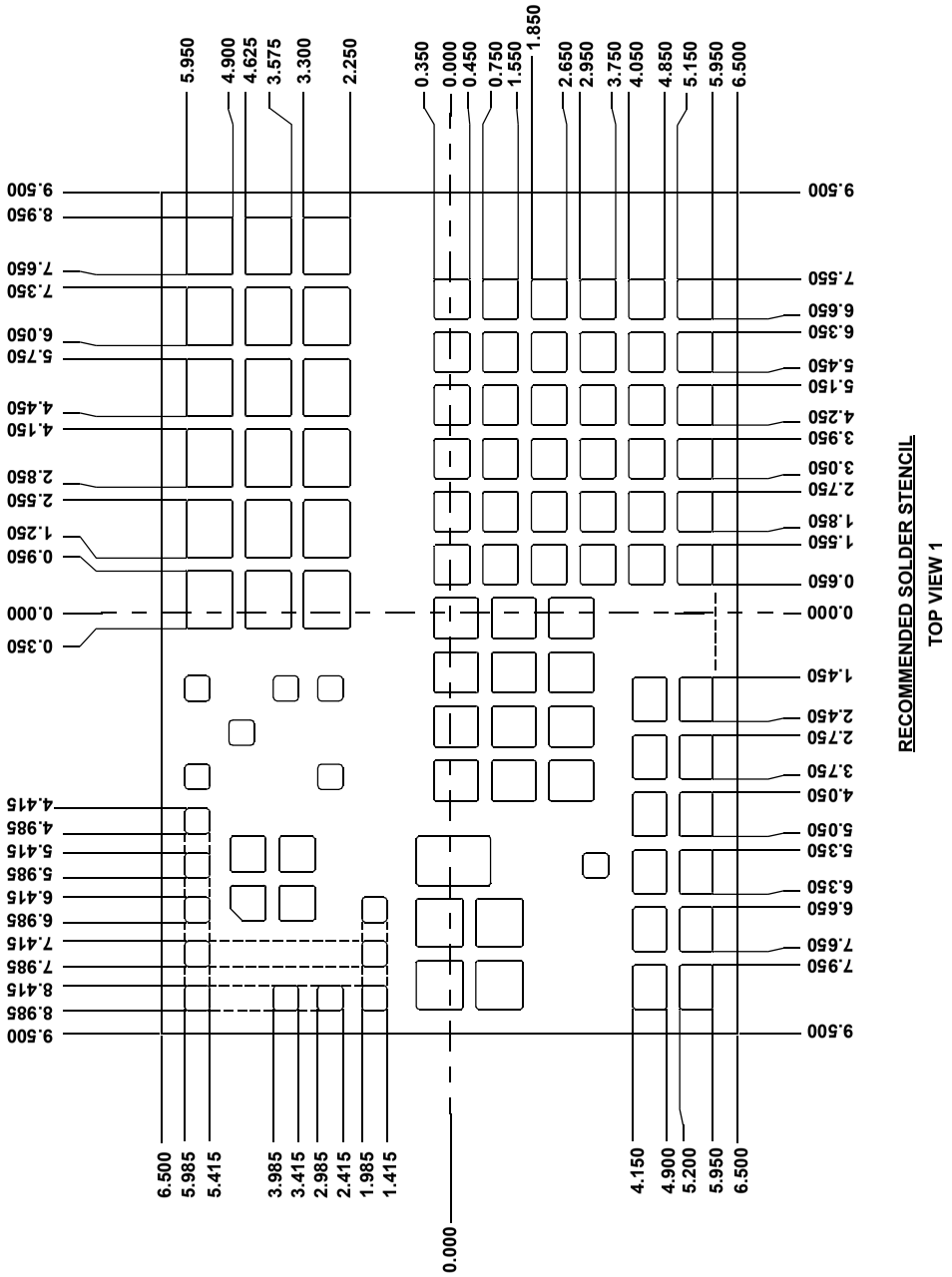
BOTTOM VIEW

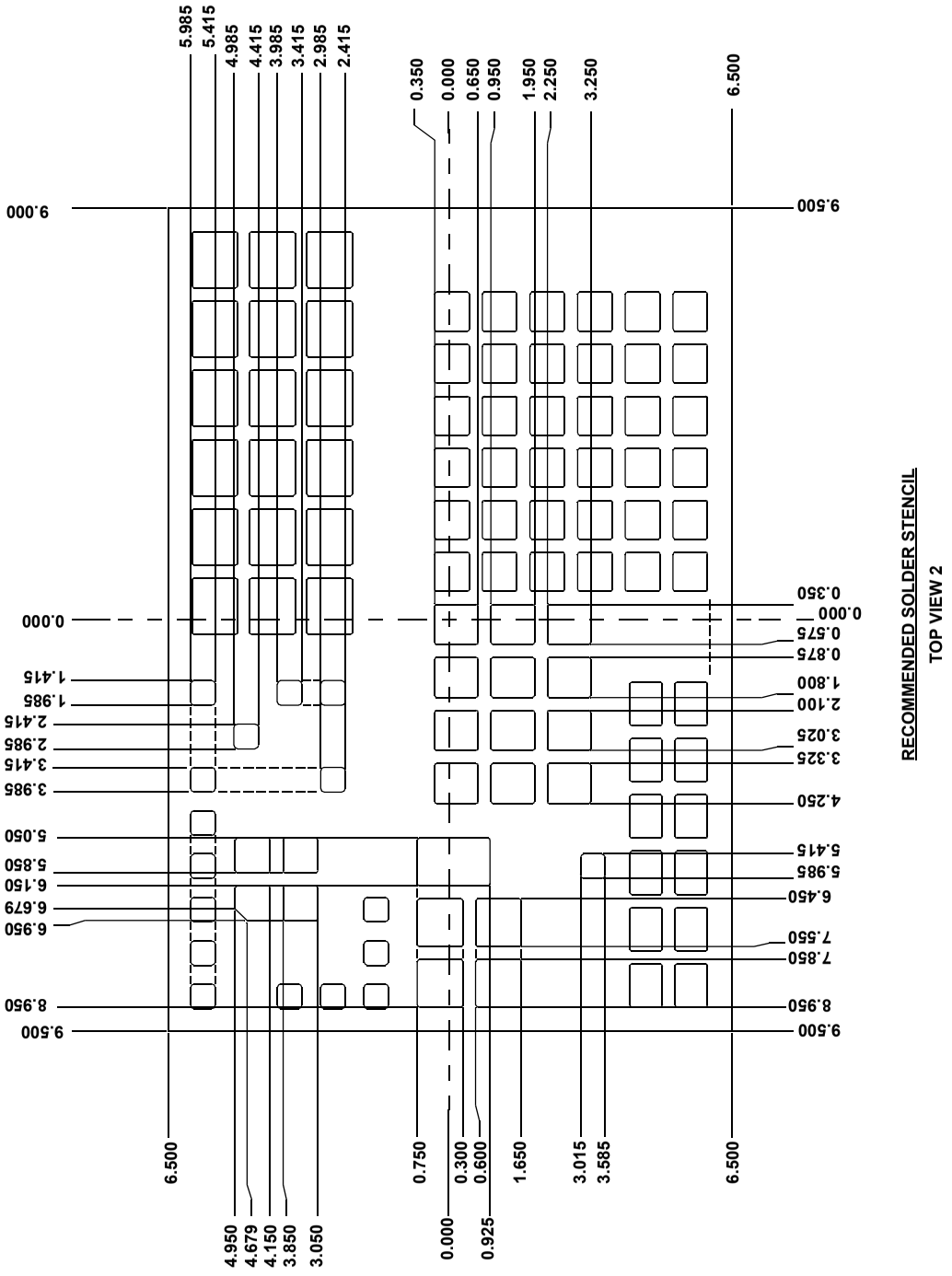


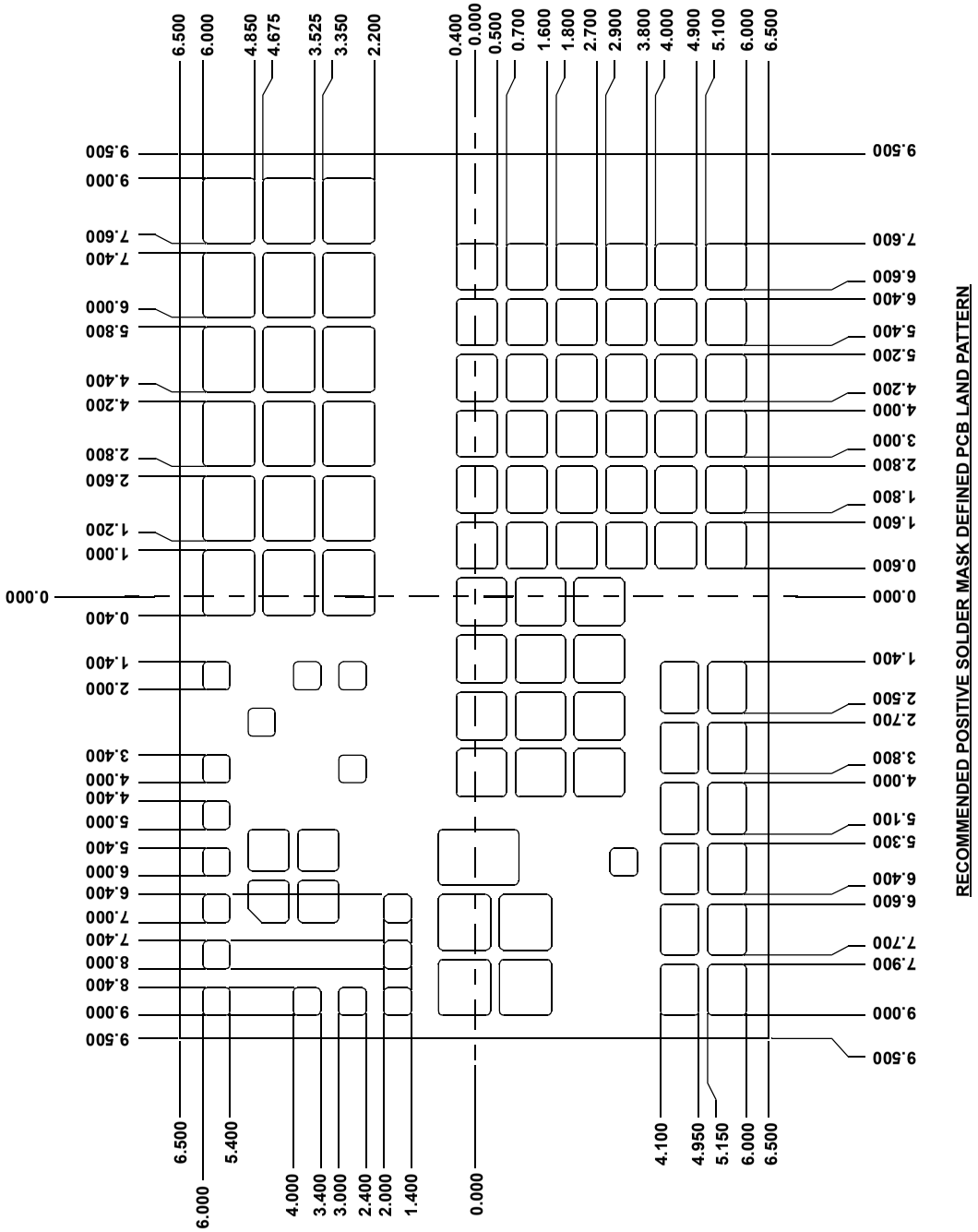
DETAIL A
(SCALE 2:1)

NOTES:

1. All dimensions are in millimeters.
2. Represents the basic land grid pitch.
3. These 17 I/Os are centered in a fixed row and column matrix at 1.0mm pitch BSC.
4. Dimensioning and tolerancing per ASME Y14.5-2009.
5. Tolerance for exposed PAD edge location dimension is ±0.1mm.

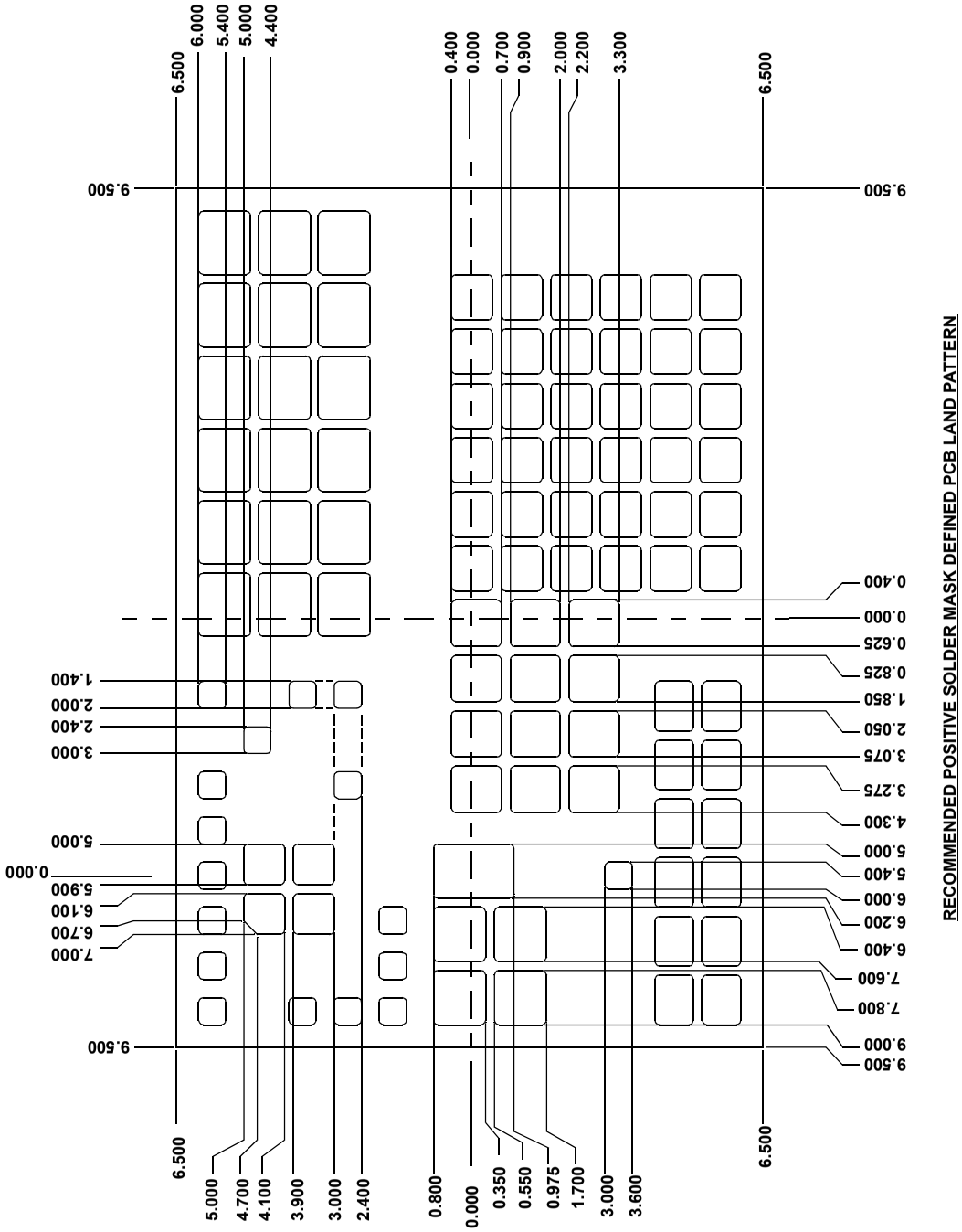

RECOMMENDED SOLDER STENCIL
TOP VIEW 1

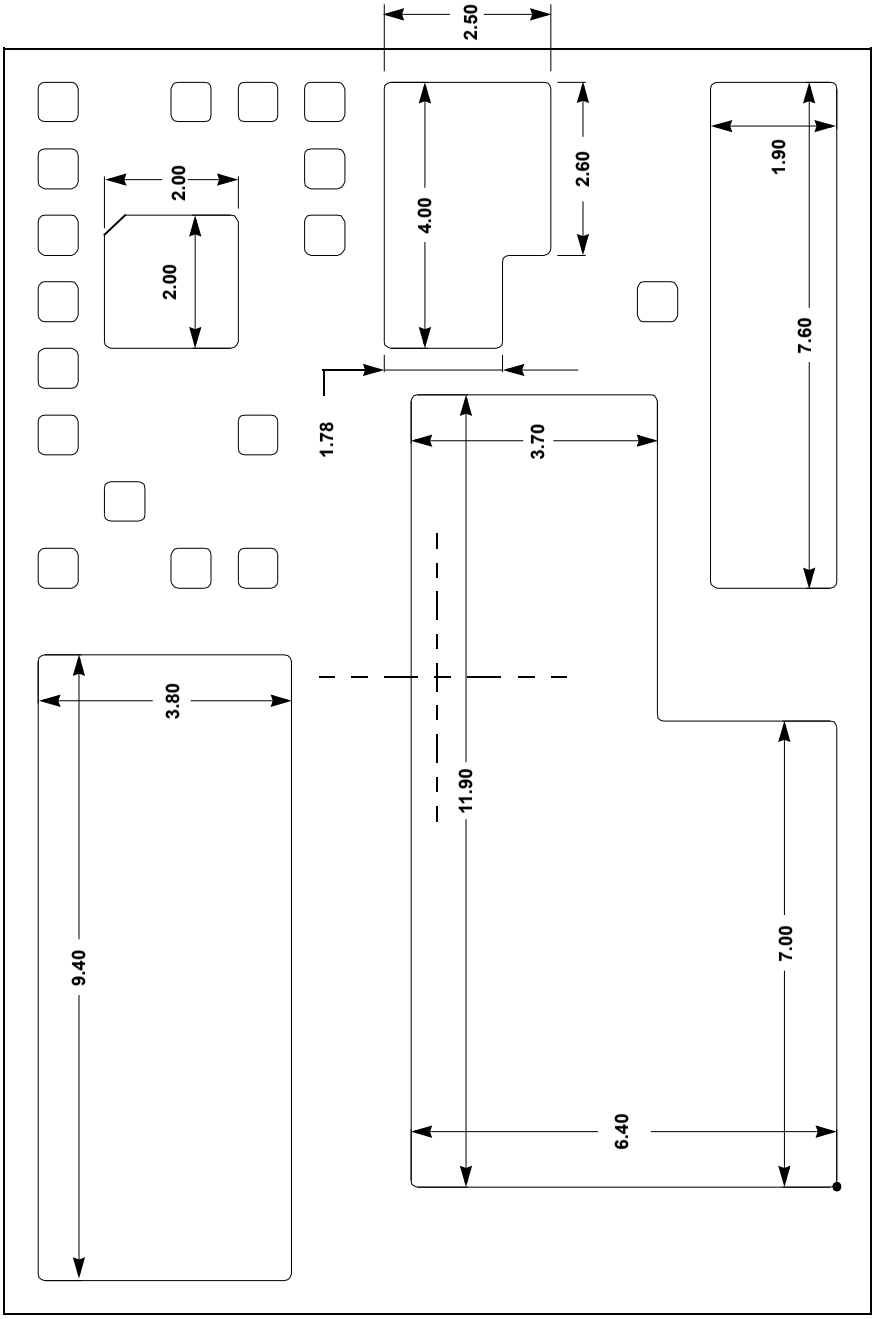

5.985
5.415
4.985
4.415
3.985
3.415
2.985
2.415
0.350
0.000
0.650
0.950
1.950
2.250
3.250
6.500
9.000
9.500
0.000
0.350
0.575
0.875
1.415
1.985
1.800
2.415
2.100
2.985
3.025
3.415
3.325
3.985
4.250
5.050
5.850
5.415
6.150
5.985
6.679
6.450
6.950
7.550
7.850
8.950
8.950
9.500
9.500
6.500
0.750
0.300
0.600
1.650
3.015
3.585
6.500
4.950
4.679
4.150
3.850
3.050
0.000
0.925
RECOMMENDED SOLDER STENCIL
TOP VIEW 2

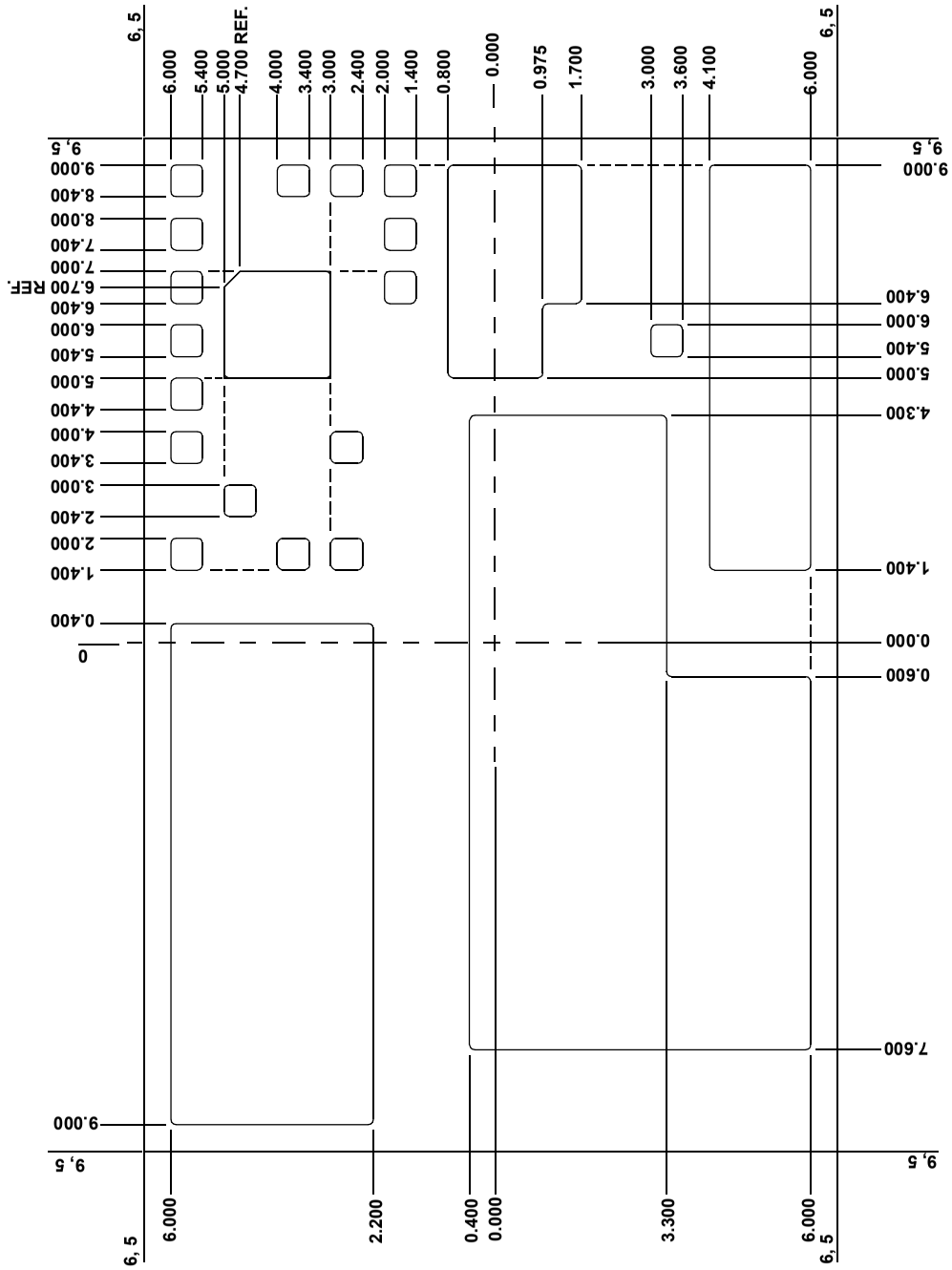


RECOMMENDED POSITIVE SOLDER MASK DEFINED PCB LAND PATTERN

TOP VIEW 1


6.500
6.000
5.400
5.000
4.400
0.400
0.000
0.700
0.900
2.000
2.200
3.300
6.500
9.500
9.500
0.400
0.000
0.625
0.825
1.850
2.050
3.075
3.275
4.300
5.000
5.400
6.000
6.200
6.400
7.600
7.800
9.000
9.500
1.400
2.000
2.400
3.000
5.000
0.000
5.900
6.100
6.700
7.000
9.500
6.500
5.000
4.700
4.100
3.900
3.000
2.400
0.800
0.000
0.350
0.550
0.975
1.700
3.000
3.600
6.500
RECOMMENDED POSITIVE SOLDER MASK DEFINED PCB LAND PATTERN
TOP VIEW 2


2.50
2.60
4.00
1.90
7.60
2.00
2.00
1.78
3.70
3.80
11.90
9.40
7.00
6.40
SIZE DETAILS FOR THE 5 EXPOSED PADS



TERMINAL AND PAD EDGE DETAILS
(BOTTOM VIEW)